## Filename: PMP9213\_REVB\_BOM.xlsx Generated: 1/28/2014 9:17:38 AM PMP9213 Rev B Bill Of Materials

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
!PCB	1		Printed Circuit Board		PMP9213	Any
C1	1	470pF	CAP, CERM, 630V, +/-10%, X7R, 1206	1206	STD	STD
C2	1	10uF	CAP, AL, 10uF, 400V, +/-20%, TH	RCAP, TH, 10 x 20mm	400BXC10MEFC10X20	Rubycon
C3	1	4.7uF	CAP, AL, 4.7uF, 400V, +/-20%, TH	RCAP, TH, 10 x 20mm		Rubycon
C4	1	330uF	CAP ALUM 330UF 25V 20% RADIAL	10x12.5mm	UHE1E331MPT6	Nichicon
C5, C9	2	1uF	CAP, CERM, 25V, +/-10%, X7R, 0805	0805	STD	STD
C6	1	2200pF	CAP, CERM, 2200pF, 250V, +/-20%, KY, Radial D8x5mm	Radial D8x5mm	DE2E3KY222MA2BM01	MuRata
C7	1	10uF	CAP, CERM, 25V, +/-10%, X5R, 1206	1206	STD	STD
C8	1	470uF	CAP ALUM 470UF 6.3V 20% RADIAL	RCAP, 6.3x8mm	RS80J471MDNASQJT	Nichicon
C10	1	DNP	Do Not Populate	0603	N/A	N/A
C13	1	0.022uF	CAP, CERM, 0.022uF, 25V, +/-10%, X7R, 0402	0402	C1005X7R1E223K	TDK
C100	1	22pF	CAP, CERM, 22pF, 50V, +/-5%, C0G/NP0, 0402	0402	GRM1555C1H220JA01D	MuRata
D1	1	600V	Diode, Switching-Bridge, 600V, 1A, DF-S	DF-S	DF06S	Vishay-Semiconductor
D2	1	1.1V	Diode, P-N, 1000V, 1A, SOD-123	SOD-123	CGRM4007-G	Comchip Technology
D3	1	0.85V	Diode, Schottky, 100V, 1A, SMA	SMA	SS110-TP	Micro Commercial Components
D4	1	100V	Diode, P-N, 100V, 0.2A, SOT-23	SOT-23	MMBD914	Fairchild Semiconductor
D5	1	0.85V	Diode, Schottky, 30V, 1A, SMA	SMA	SS13-TP	Micro Commercial Components
L1	1	33uH	Inductor, Wirewound, Ferrite, 33uH, 0.13A, 0.7 ohm, SMD	2.5x1.8x1.8mm	CB2518T330K	Taiyo Yuden
Q1	1	600V	MOSFET, N-CH, 600V, 0.18A, TO-226AA	TO-226AA	FQN1N60CTA	Fairchild Semiconductor
R1	1	300k	RES, 5%, 0.25W, 1206	1206	STD	STD
R2	1	200	RES, 5%, 0.125W, 0805	0805	STD	STD
R3	1	20	RES, 1%, 0.1W, 0603	0603	STD	STD
R4	1	2.49k	RES, 2.49k ohm, 1%, 0.1W, 0603	0603	CRCW06032K49FKEA	Vishay-Dale
R5	1	60.4k	RES, 60.4k ohm, 1%, 0.063W, 0402	0402	CRCW040260K4FKED	Vishay-Dale
R6, R9	2	1.0k	RES, 1.0k ohm, 5%, 0.063W, 0402	0402	CRCW04021K00JNED	Vishay-Dale
R7	1	21.5k	RES, 21.5k ohm, 1%, 0.063W, 0402	0402	CRCW040221K5FKED	Vishay-Dale
R8	1	2.0	RES, 2.0 ohm, 5%, 0.125W, 0805	0805	CRCW08052R00JNEA	Vishay-Dale
R10	1	0	RES, 1%, 0.063W, 0402	0402	STD	STD
R11, R13, R100	3	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale
R12	1	6.04k	RES, 1%, 0.063W, 0402	0402	STD	STD
R14	1	30.1k	RES, 30.1k ohm, 1%, 0.063W, 0402	0402	CRCW040230K1FKED	Vishay-Dale
R15	1	DNP	Do Not Populate	0805	N/A	N/A
RF1	1	22	RES, 22 ohm, 10%, 2W, Fusible, TH	Axial resistor	EMC2-22RKI	TT Electronics/IRC
T1	1	1.8mH	Transformer, 1.8mH, TH	17x15x16mm	G134043LF	GCI Technologies
TP1, TP2	2	White	Test Point, TH, Miniature, White	Keystone5002	5002	Keystone
TP3, TP5	2	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP4, TP6	2	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1		Constant-Voltage, Constant-Current Flyback Controller Using Opto-	D0007A	UCC28740D	Texas Instruments
			Coupler Feedback, D0007A			
U2	1		LOW-VOLTAGE ADJUSTABLE PRECISION SHUNT REGULATOR,	DBZ0003A	TLV431AIDBZ	Texas Instruments
			DBZ0003A			
U3	1		Opto-Isolator, 1 Channel, SMT	DIP-4	LTV-817S	Lite-On

## Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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